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updates Sept. 17 & Oct. 3 & Oct. 27 in bold red

TPS544C20 EVM with Dynamic Load

D ! t	0	. V-I	Description	Deeles - Defenses	D	Mft	I Alta and a table and be a second	Alt
PCB1	Quantity	Value	Description Printed Circuit Board	PackageReference	PartNumber PMP10364	Manufacturer	Alternate PartNumber	Alternate Manufacturer
C1, C3	2	Open	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402	C1005X7R1E103K	Any TDK		
C2, C10,	3	1000pF	CAP, CERM, 0.010F, 25V, +/-10%, X7R, 0402 CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0402	0402	C1005X7R1E103K	TDK		
C16	3	Тооорі	OAI , CERW, 1000pi , 30 V, 47-10 %, X/TK, 0402	0402	C1005X/1(1111021(TBR		
C4	1	0.01uF	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402	C1005X7R1E103K	TDK		
C5	1	330pF	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0402	0402	C1005C0G1H331J	TDK		
C6	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E105KA12	MuRata		
					D			
C7	1	4.7uF	CAP, CERM, 4.7uF, 10V, +/-20%, X5R, 0402	0402	GRM155R61A475M	MuRata		
C8, C23	2	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A105KE15	MuRata		
_		_			D			
C9	1	0.1uF	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0402	0402	GRM155R61E104KA87	MuRata		
C11, C12,	4	22uF	CAP, CERM, 22 µF, 16 V, +/- 20%, X5R, 1210	1210	C3225X5R1C226M	TDK	C3225X5R1C226K or	must have at least 10uF
C13, C14	4	ZZUF	CAP, CERM, 22 µP, 16 V, +/- 20%, ASK, 1210	1210	C3223A3R I C226W	IDK	C3225X5R1C226R or C3225X7R1C226M or	with 12V bias
C13, C14							C3225X7R1C226W 0F	with 12V bias
C15	1	0.1uF	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	0603	C0603C104J3RACTU	Kemet	C3223A/K IC220K OK	
C17, C18	2	100uF	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210	C1210C107M9PACTU	Kemet		
C19, C20	2	470uF	CAP, AL, 470uF, 2.5V, +/-20%, 9 ohm, SMD	7.3x1.8x4.3mm	EEFSX0E471ER	Panasonic		
C21	1	470uF	CAP, AL, 470uF, 25V, +/-20%, 0.03 ohm, TH	8.0x20mm	EEU-FM1E471LBJ	Panasonic	see note 2 below	
C22, C24,	4	0.1uF	CAP, CERM, 0.1uF, 50V, +/-20%, X7R, 0402	0402	C1005X7R1H104M	TDK		
C25, C26								
C27	0	DNP						
D1, D2	2	30V	Diode, Schottky, 30V, 0.5A, SOD-123	SOD-123	MBR0530T1G	ON Semiconductor		
D3	1	Red	LED, Red, SMD	LED_0805	LTST-C170KRKT	Lite-On		
D4	1	30V	Diode, Schottky, 30V, 0.2A, SOD-323	SOD-323	BAT54WS-7-F	Diodes Inc.		
H1, H2, H3,	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips	Screw	NY PMS 440 0025 PH	B&F Fastener Supply		
H4	4		panhead Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Kovetono		
H5, H6, H7, H8	4		Standon, Flex, U.S L #4-40 NYION	Sidiluoli	19020	Keystone	1	
H9, H10,	4		Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon	SJ-5303 (CLEAR)	3M		
H11, H12	-		Dampon, Homophoro, 0.44 A 0.20, Olean	anoparoni bumpun	SO SOOD (OLLAIV)			
J1	1		Header (shrouded), 100mil, 5x2, Gold, TH	5x2 Shrouded header	5103308-1	TE Connectivity		
			, , , , , , , , , , , , , , , , , , , ,			, ,	Ì	
J2	1		Connector, DC Jack 2.1X5.5 mm, TH	POWER JACK,	PJ-102A	CUI Inc.		
				14.4x11x9mm				
J3	1		TERMINAL BLOCK 5.08MM VERT 2POS	TERM_BLK, 2pos,	ED120/2DS	On-Shore Technology	<u> </u>	
				5.08mm			ļ	
J4	1	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins		
L1	1	330nH	Inductor, Ferrite, 330nH, 32.8A, 0.00033 ohm, SMD	SMD, 2-Leads, Body	VLB10090HT-R33K-B2	TDK	Ì	
LBL1	-		Thermal Transfer Drintohla Labela 0.0508 M 0.0008	10.2x10mm	THT-14-423-10	Dradu		
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	ID1-14-423-10	Brady		
Q1	1	0.2V	Transistor, NPN, 40V, 0.2A, SOT-23	0.200°W SOT-23	MMBT3904	Fairchild Semiconductor		
Q2	1	25V	MOSFET, N-CH, 25V, 40A, SON 5x6mm	SON 5x6mm	CSD16556Q5B	Texas Instruments		None
R1	1	100k	RES, 100k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale		Tionic
R2, R4	2	Open	RES, 20.0k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale Vishay-Dale		
R2, R4	1	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	ERJ-2GE0R00X	Panasonic		
R5	1	Open	RES, 0 ohm, 5%, 0.063W, 0402	0402	ERJ-2GE0R00X	Panasonic		
R6	1	20.0k	RES, 20.0k ohm, 1%, 0.063W, 0402	0402	CRCW040220K0FKED	Vishay-Dale		
R7, R13,	3	49.9	RES, 49.9 ohm, 1%, 0.063W, 0402	0402	CRCW040249R9FKED	Vishay-Dale Vishay-Dale		
R15	-		, , , , , , , , , , , , , , , , , , , ,			.,		
R8	1	27.4k	RES, 27.4 k, 1%, 0.063 W, 0402	0402	CRCW040227K4FKED	Vishay-Dale		
R9	1	30.1k	RES, 30.1k ohm, 1%, 0.063W, 0402	0402	CRCW040230K1FKED	Vishay-Dale		
R10, R17	2	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	RC0402JR-070RL	Yageo America		
R11, R12	2	38.3k	RES, 38.3k ohm, 1%, 0.063W, 0402	0402	CRCW040238K3FKED	Vishay-Dale		
R14	1	2.2	RES, 2.2 ohm, 5%, 0.063W, 0402	0402	CRCW04022R20JNED	Vishay-Dale		
R16	1	1	RES, 1.0 ohm, 5%, 0.25W, 1206	1206	CRCW12061R00JNEA	Vishay-Dale		
R18, R20,	3	0.02	RES, 0.02 ohm, 1%, 2W, 2512	2512	CSRN2512FK20L0	Stackpole Electronics Inc	1	
R21	_	4 001	DEO 4 001 1 40/ 0 005*** - ***	0.400	000000000000000000000000000000000000000	Vielen Dele		
R19, R22	2	1.00k	RES, 1.00k ohm, 1%, 0.063W, 0402	0402	CRCW04021K00FKED	Vishay-Dale		
R23	1	8.06k	RES, 8.06k ohm, 1%, 0.063W, 0402	0402	CRCW04028K06FKED	Vishay-Dale		
R24	1	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R25	1	200k	RES, 200k ohm, 1%, 0.063W, 0402	0402	CRCW0402200KFKED CRCW0402330RJNED	Vishay-Dale	1	
R27 R100	1	330	RES, 330 ohm, 5%, 0.063W, 0402	0402 0805	ERJ-6RQFR22V	,	and mate 0 to low	
T1, T2	2	0.22 50A	RES, 0.22 ohm, 1%, 0.125W, 0805 Terminal 50A Lug	CB35-36-CY	CB35-36-CY	Panasonic Panduit	see note 2 below	
TP1, TP2,	8	Red	Test Point, Miniature, Red, TH	Red Miniature	5000	Keystone		
TP3, TP4,	0	Nou	100t Fortt, Williature, 100t, FF	Testpoint	5550	Troystone	Ì	
TP5, TP6,				1 corpoint			Ì	
TP7, TP8				Ì			Ì	
TP9, TP10,	3	Black	Test Point, Miniature, Black, TH	Black Miniature	5001	Keystone		
TP11				Testpoint				
TP12	1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone		
U1	1		TPS544C20 18V, 30A PMBUS SYNCHRONOUS	RVF0040A	TPS544C20RVF	Texas Instruments	None	None
			BUCK CONVERTERS, RVF0040A					
U2	1	UCC37324D	IC, Dual 4-A High Speed Low-Side Power MOSFET	SO-8	UCC37324D	TI	None	None
L			Drivers			7.		h.
U3	1	TLC555CD	IC, Timer, Low-Power CMOS	SO8	TLC555CD	TI	None	None
	0	I	Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A	Ì	
FID1, FID2,								
FID3		Notes:					ı	

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^{1.} Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

^{2.} C21 & R100 in series added by hand on either top or bottom of board $\,$

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